

512K x 8 HIGH-SPEED CMOS STATIC RAM

JULY 2001

FEATURES

- High-speed access times:
10, 12 and 15 ns
- High-performance, low-power CMOS process
- Multiple center power and ground pins for greater noise immunity
- Easy memory expansion with $\overline{CE}$ and $\overline{OE}$ options
- $\overline{CE}$ power-down
- Fully static operation: no clock or refresh required
- TTL compatible inputs and outputs
- Single 3.3V power supply
- Packages available:
 - 36-pin 400-mil SOJ
 - 36-pin miniBGA
 - 44-pin TSOP (Type II)

DESCRIPTION

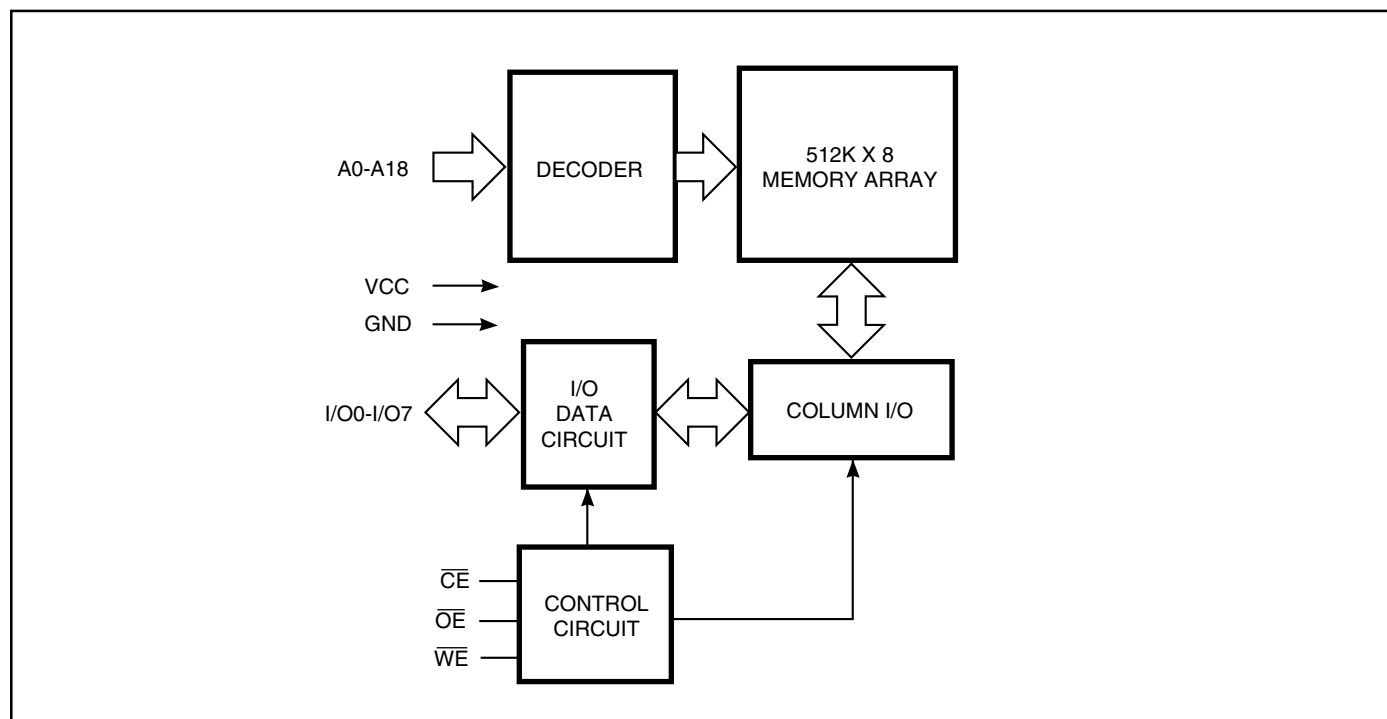
The *ISSI* IS61LV5128 is a very high-speed, low power, 524,288-word by 8-bit CMOS static RAM. The IS61LV5128 is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields higher performance and low power consumption devices.

When $\overline{CE}$ is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down to 250 μ W (typical) with CMOS input levels.

The IS61LV5128 operates from a single 3.3V power supply and all inputs are TTL-compatible.

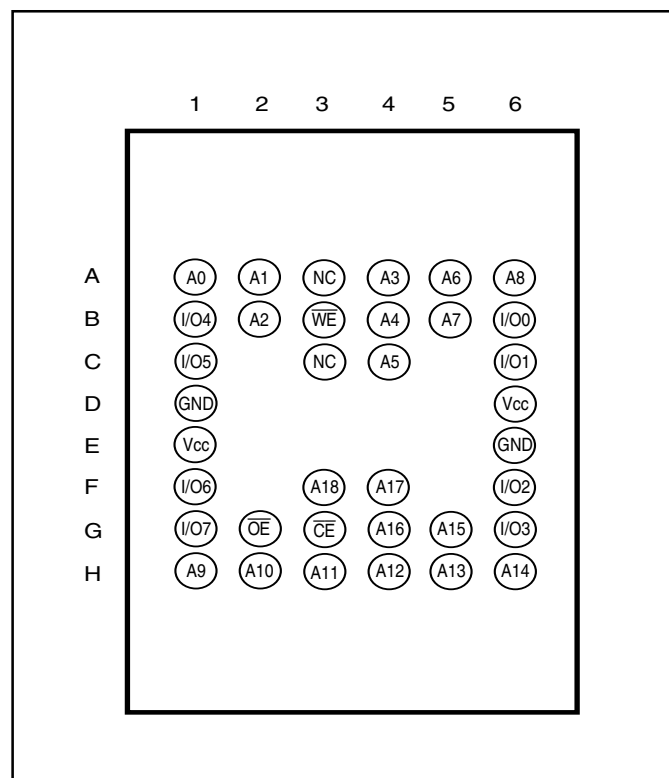
The IS61LV5128 is available in 36-pin 400-mil SOJ, 36-pin mini BGA, and 44-pin TSOP (Type II) packages.

FUNCTIONAL BLOCK DIAGRAM



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36 mini BGA



Pin	Function	Pin	Function
1	NC	44	NC
2	NC	43	NC
3	A0	42	NC
4	A1	41	A18
5	A2	40	A17
6	A3	39	A16
7	A4	38	A15
8	CE	37	OE
9	I/O0	36	I/O7
10	I/O1	35	I/O6
11	Vcc	34	GND
12	GND	33	Vcc
13	I/O2	32	I/O5
14	I/O3	31	I/O4
15	WE	30	A14
16	A5	29	A13
17	A6	28	A12
18	A7	27	A11
19	A8	26	A10
20	A9	25	NC
21	NC	24	NC
22	NC	23	NC

A0-A18	Address Inputs
$\overline{CE}$	Chip Enable Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
I/O0-I/O7	Bidirectional Ports
Vcc	Power
GND	Ground
NC	No Connection

Mode	$\overline{WE}$	$\overline{OE}$	$\overline{OE}$	I/O Operation	Vcc Current
Not Selected (Power-down)	X	H	X	High-Z	ISB1, ISB2
Output Disabled	H	L	H	High-Z	ICC
Read	H	L	L	DOUT	ICC
Write	L	L	X	DIN	ICC

Pin	Function
1	A0
2	A1
3	A2
4	A3
5	A4
6	CE
7	I/O0
8	I/O1
9	Vcc
10	GND
11	I/O2
12	I/O3
13	WE
14	A5
15	A6
16	A7
17	A8
18	A9
19	NC
20	A10
21	A11
22	A12
23	A13
24	A14
25	I/O4
26	I/O5
27	Vcc
28	GND
29	I/O6
30	I/O7
31	OE
32	A15
33	A16
34	A17
35	A18
36	NC

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
V _{TERM}	Terminal Voltage with Respect to GND	−0.5 to V _{CC} + 0.5	V
T _{BIAS}	Temperature Under Bias	−55 to +125	°C
T _{STG}	Storage Temperature	−65 to +150	°C
P _T	Power Dissipation	1.0	W

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

Range	Ambient Temperature	10 ns V _{CC}	12 ns, 15 ns V _{CC}
Commercial	0°C to +70°C	3.3V +10%, -5%	3.3V ± 10%
Industrial	−40°C to +85°C	3.3V +10%, -5%	3.3V ± 10%

CAPACITANCE^(1,2)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{I/O}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{CC} = 3.3V.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit	
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = −4.0 mA	2.4	—	V	
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA	—	0.4	V	
V _{IH}	Input HIGH Voltage		2.0	V _{CC} + 0.3	V	
V _{IL}	Input LOW Voltage ⁽¹⁾		−0.3	0.8	V	
I _{LI}	Input Leakage	GND ≤ V _{IN} ≤ V _{CC}	Com. Ind.	−1 5	1 5	μA
I _{LO}	Output Leakage	GND ≤ V _{OUT} ≤ V _{CC} , Outputs Disabled	Com. Ind.	−1 −5	1 5	μA

Note:

1. V_{IL} = -3.0V for pulse width less than 10 ns.

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions		-10 ns		-12 ns		-15 ns		Unit
				Min.	Max.	Min.	Max.	Min.	Max.	
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., $\overline{CE} = V_{IL}$ I _{OUT} = 0 mA, f = f _{MAX} .	Com.	—	145	—	135	—	125	mA
			Ind.	—	155	—	145	—	135	
I _{SB}	TTL Standby Current (TTL Inputs)	V _{CC} = Max., V _{IN} = V _{IH} or V _{IL} $\overline{CE} \geq V_{IH}$, f = f _{MAX} .	Com.	—	70	—	60	—	50	mA
			Ind.	—	80	—	70	—	60	
I _{SB1}	TTL Standby Current (TTL Inputs)	V _{CC} = Max., V _{IN} = V _{IH} or V _{IL} $\overline{CE} \geq V_{IH}$, f = 0	Com.	—	20	—	20	—	20	mA
			Ind.	—	25	—	25	—	25	
I _{SB2}	CMOS Standby Current (CMOS Inputs)	V _{CC} = Max., $\overline{CE} \leq V_{CC} - 0.2V$, V _{IN} ≥ V _{CC} - 0.2V, or V _{IN} ≤ 0.2V, f = 0	Com.	—	10	—	10	—	10	mA
			Ind.	—	15	—	15	—	15	

Note:

1. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

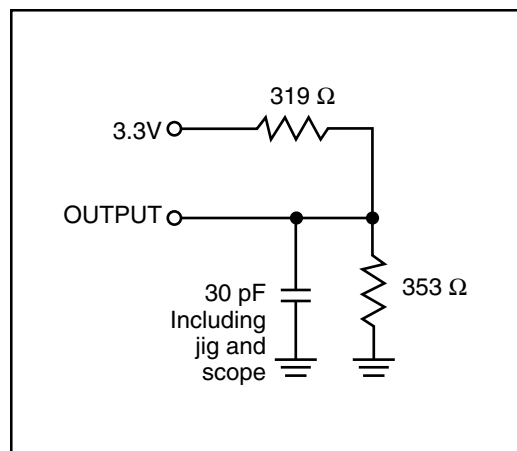
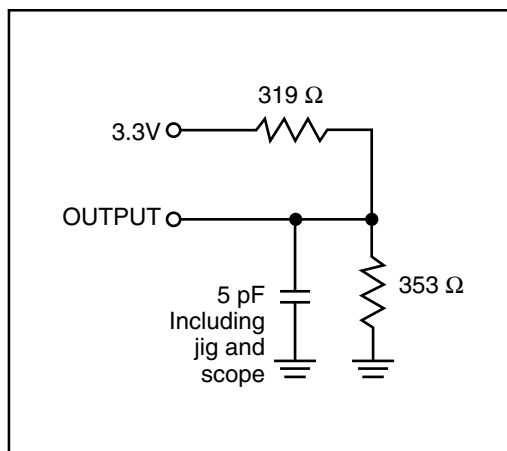
Symbol	Parameter	-10 ns		-12 ns		-15 ns		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{RC}	Read Cycle Time	10	—	12	—	15	—	ns
t _{AA}	Address Access Time	—	10	—	12	—	15	ns
t _{OHA}	Output Hold Time	3	—	3	—	3	—	ns
t _{ACE}	$\overline{\text{CE}}$ Access Time	—	10	—	12	—	15	ns
t _{DOE}	$\overline{\text{OE}}$ Access Time	—	4	—	5	—	7	ns
t _{LZOE⁽²⁾}	$\overline{\text{OE}}$ to Low-Z Output	0	—	0	—	0	—	ns
t _{HZOE⁽²⁾}	$\overline{\text{OE}}$ to High-Z Output	0	4	0	5	0	6	ns
t _{LZCE⁽²⁾}	$\overline{\text{CE}}$ to Low-Z Output	3	—	3	—	3	—	ns
t _{HZCE⁽²⁾}	$\overline{\text{CE}}$ to High-Z Output	0	4	0	6	0	8	ns
t _{PU}	Power Up Time	0	—	0	—	0	—	ns
t _{PD}	Power Down Time	—	10	—	12	—	15	ns

Notes:

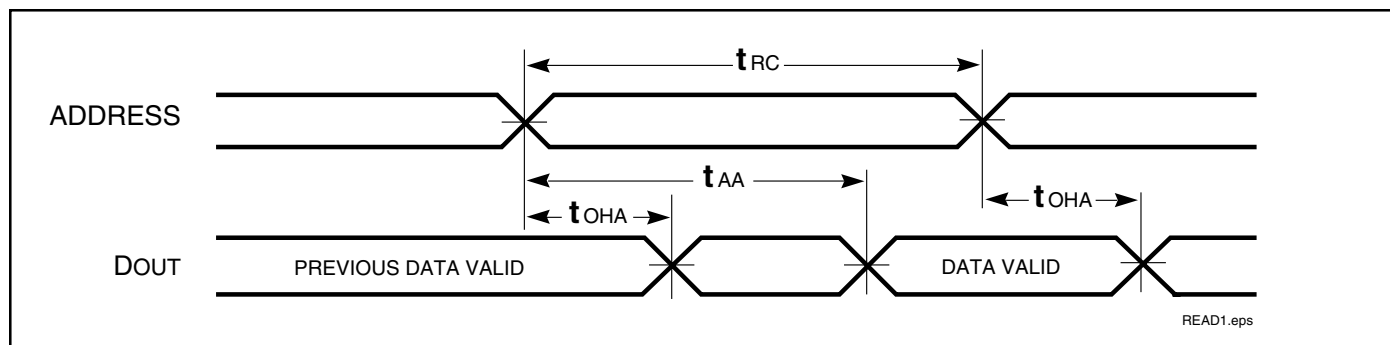
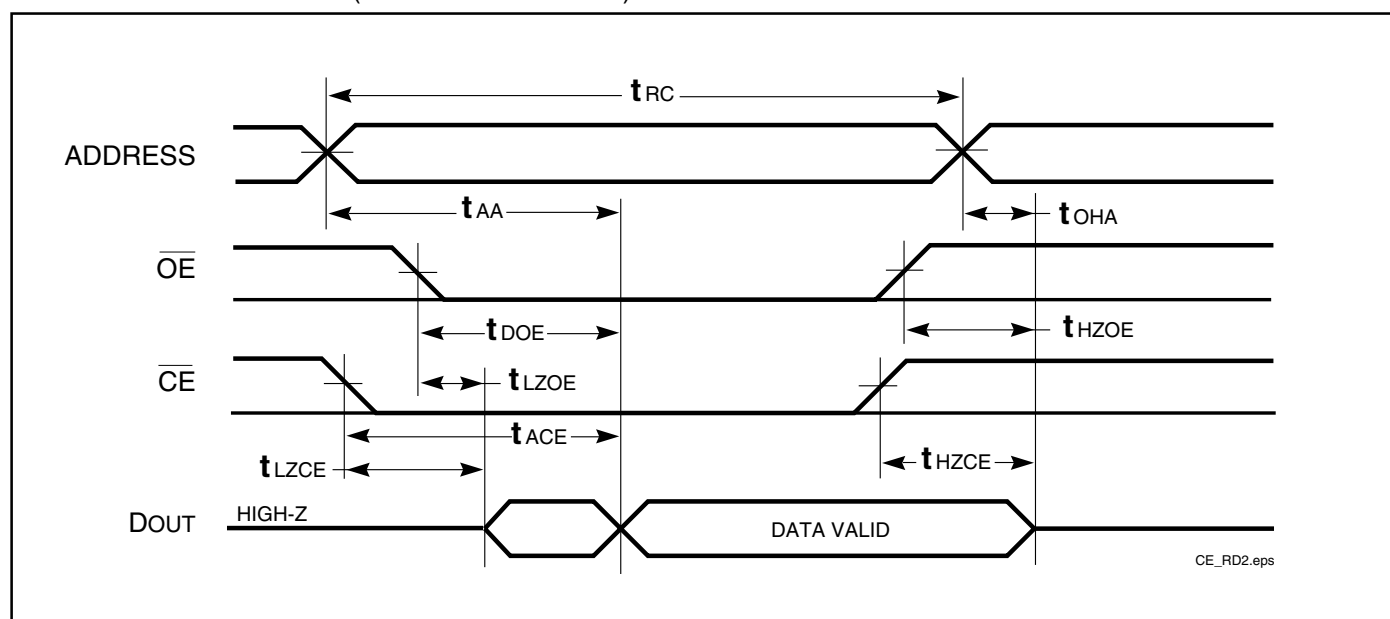
1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.

AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Levels	1.5V
Output Load	See Figures 1 and 2

AC TEST LOADS**Figure 1****Figure 2**

AC WAVEFORMS

READ CYCLE NO. 1^(1,2) (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$)READ CYCLE NO. 2^(1,3) ($\overline{CE}$ and $\overline{OE}$ Controlled)

Notes:

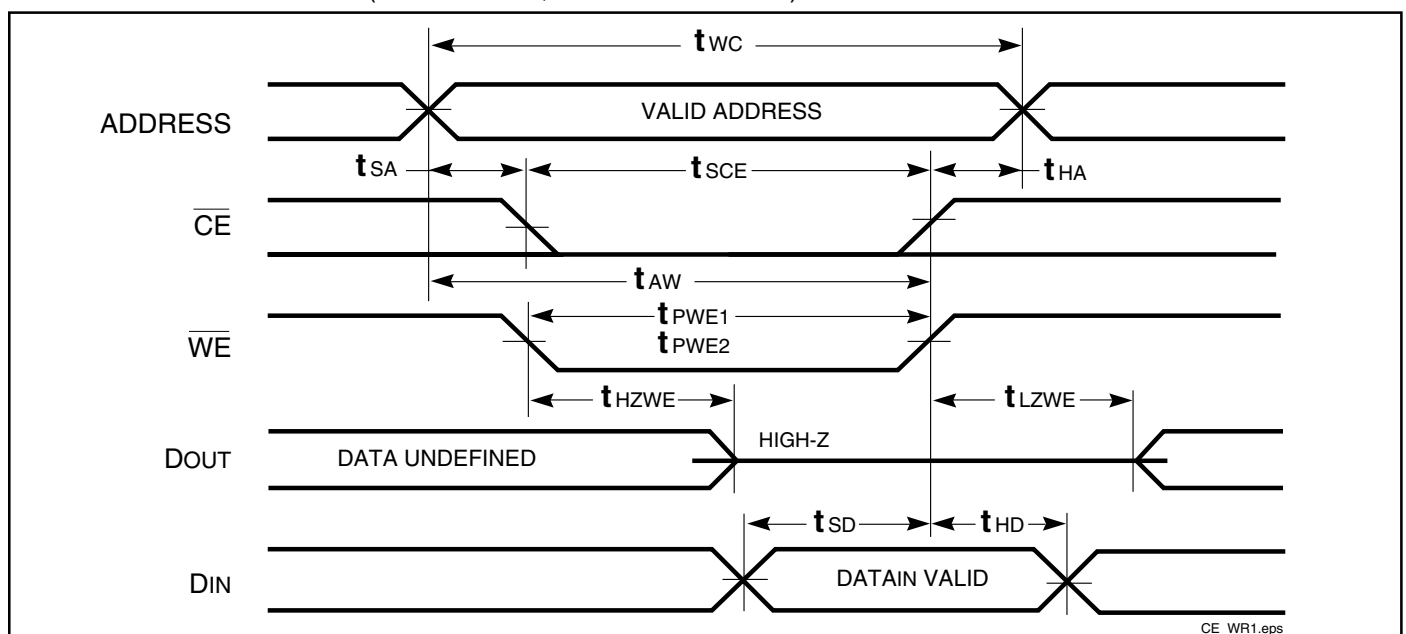
1. $\overline{WE}$ is HIGH for a Read Cycle.
2. The device is continuously selected. $\overline{OE}$, $\overline{CE} = V_{IL}$.
3. Address is valid prior to or coincident with $\overline{CE}$ LOW transitions.

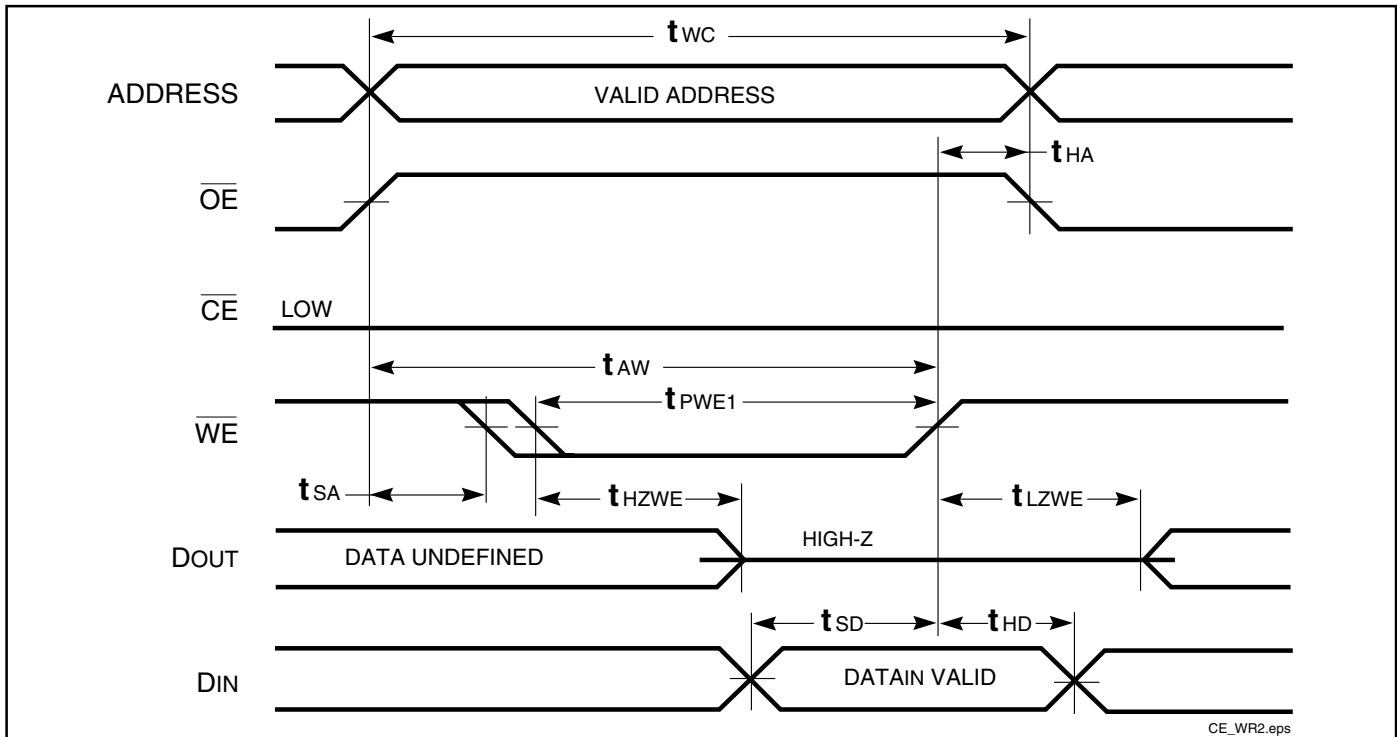
WRITE CYCLE SWITCHING CHARACTERISTICS^(1,3) (Over Operating Range)

Symbol	Parameter	-10 ns		-12 ns		-15 ns		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{WC}	Write Cycle Time	10	—	12	—	15	—	ns
t _{SCE}	$\overline{CE}$ to Write End	8	—	9	—	10	—	ns
t _{AW}	Address Setup Time to Write End	8	—	9	—	10	—	ns
t _{HA}	Address Hold from Write End	0	—	0	—	0	—	ns
t _{SA}	Address Setup Time	0	—	0	—	0	—	ns
t _{PWE1} ⁽⁴⁾	$\overline{WE}$ Pulse Width	8	—	8	—	10	—	ns
t _{PWE2}	$\overline{WE}$ Pulse Width ($\overline{OE}$ = LOW)	10	—	12	—	12	—	ns
t _{SD}	Data Setup to Write End	6	—	6	—	7	—	ns
t _{HD}	Data Hold from Write End	0	—	0	—	0	—	ns
t _{HZWE} ⁽²⁾	$\overline{WE}$ LOW to High-Z Output	0	5	0	6	0	7	ns
t _{LZWE} ⁽²⁾	$\overline{WE}$ HIGH to Low-Z Output	0	—	0	—	0	—	ns

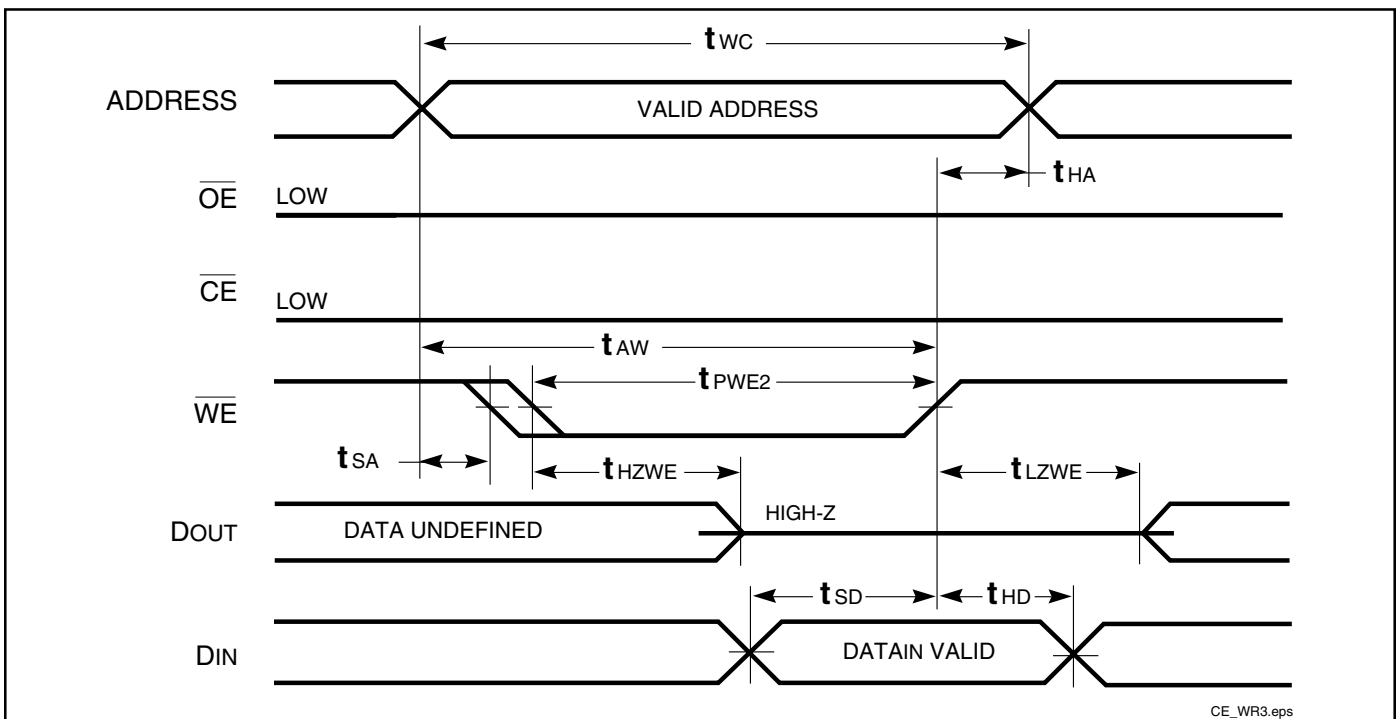
Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
4. Tested with $\overline{OE}$ HIGH.

AC WAVEFORMS**WRITE CYCLE NO. 1^(1,2)** ($\overline{CE}$ Controlled, $\overline{OE}$ = HIGH or LOW)

WRITE CYCLE NO. 2^(1,2) ($\overline{WE}$ Controlled: $\overline{OE}$ is HIGH During Write Cycle)**Notes:**

1. The internal write time is defined by the overlap of $\overline{CE}$ LOW and $\overline{WE}$ LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if $\overline{OE} \bullet V_{IH}$.

WRITE CYCLE NO. 3 ($\overline{WE}$ Controlled: $\overline{OE}$ is LOW During Write Cycle)

ORDERING INFORMATION**Commercial Range: 0°C to +70°C**

Speed (ns)	Order Part No.	Package
10	IS61LV5128-10K	400-mil Plastic SOJ
10	IS61LV5128-10T	TSOP (Type II)
10	IS61LV5128-10B	mini BGA (8mmx10mm)
12	IS61LV5128-12K	400-mil Plastic SOJ
12	IS61LV5128-12T	TSOP (Type II)
12	IS61LV5128-12B	mini BGA (8mmx10mm)
15	IS61LV5128-15K	400-mil Plastic SOJ
15	IS61LV5128-15T	TSOP (Type II)
15	IS61LV5128-15B	mini BGA (8mmx10mm)

Industrial Range: -40°C to +85°C

Speed (ns)	Order Part No.	Package
10	IS61LV5128-10KI	400-mil Plastic SOJ
10	IS61LV5128-10TI	TSOP (Type II)
10	IS61LV5128-10BI	mini BGA (8mmx10mm)
12	IS61LV5128-12KI	400-mil Plastic SOJ
12	IS61LV5128-12TI	TSOP (Type II)
12	IS61LV5128-12BI	mini BGA (8mmx10mm)
15	IS61LV5128-15KI	400-mil Plastic SOJ
15	IS61LV5128-15TI	TSOP (Type II)
15	IS61LV5128-15BI	mini BGA (8mmx10mm)

ISSI®**Integrated Silicon Solution, Inc.**

2231 Lawson Lane
Santa Clara, CA 95054
Tel: 1-800-379-4774
Fax: (408) 588-0806
E-mail: sales@issi.com
www.issi.com